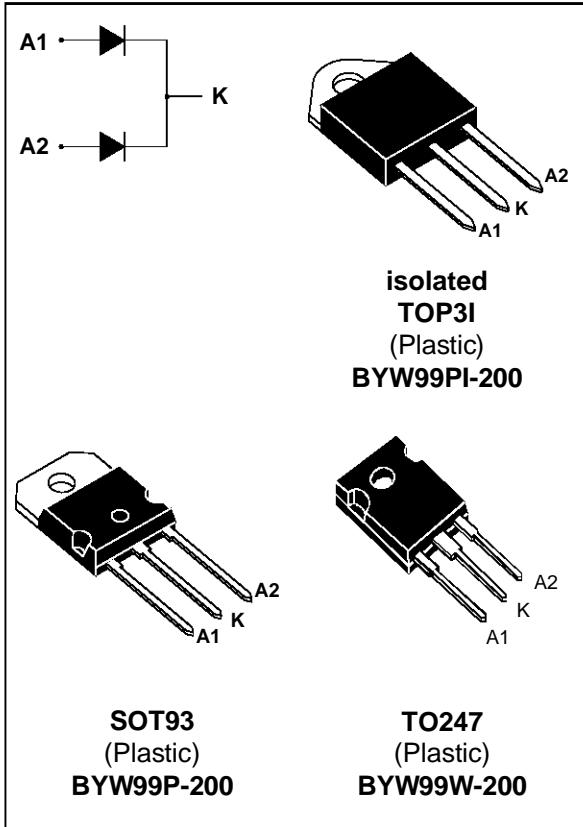


## HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

### FEATURES

PRELIMINARY DATASHEET

- SUITED FOR SMPS
- VERY LOW FORWARD LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY
- INSULATED VERSION TOP3I :  
Insulating voltage = 2500 V DC  
Capacitance = 12 pF



### DESCRIPTION

Dual center tap rectifier suited for switchmode power supply and high frequency DC to DC converters.

Packaged in SOT93, TOP3I or TO247 this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter				Value	Unit
$I_F(\text{RMS})$	RMS forward current			Per diode	35	A
$I_F(\text{AV})$	Average forward current $\delta = 0.5$	SOT93 / TO247	T <sub>c</sub> =120°C	Per diode	15	A
		TOP3I	T <sub>c</sub> =115°C	Per diode	15	
$I_{FSM}$	Surge non repetitive forward current		tp=10ms sinusoidal	Per diode	200	A
$T_{\text{stg}}$ $T_j$	Storage and junction temperature range			- 40 to + 150	°C	
				- 40 to + 150		°C

Symbol	Parameter	BYW99P-/PI-/W-				Unit
		50	100	150	200	
$V_{RRM}$	Repetitive peak reverse voltage	50	100	150	200	V

## BYW99P/PI/W

### THERMAL RESISTANCE

Symbol	Parameter			Value	Unit
Rth (j-c)	Junction to case	SOT93 / TO247	Per diode	1.8	°C/W
			Total	1.0	
	TOP3I	Per diode	2.0		
			Total	1.25	
Rth (c)	Coupling	SOT93 / TO247		0.2	°C/W
		TOP3I		0.5	

When the diodes 1 and 2 are used simultaneously :

$$T_j - T_c \text{ (diode 1)} = P(\text{diode 1}) \times R_{\text{th(j-c)}} \text{ (Per diode)} + P(\text{diode 2}) \times R_{\text{th(c)}}$$

### ELECTRICAL CHARACTERISTICS (Per diode)

#### STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> *	T <sub>j</sub> = 25°C	V <sub>R</sub> = V <sub>RRM</sub>			20	μA
	T <sub>j</sub> = 100°C				1.5	mA
V <sub>F</sub> **	T <sub>j</sub> = 125°C	I <sub>F</sub> = 12 A			0.85	V
	T <sub>j</sub> = 125°C	I <sub>F</sub> = 25 A			1.05	
	T <sub>j</sub> = 25°C	I <sub>F</sub> = 25 A			1.15	

Pulse test : \* tp = 5 ms, duty cycle < 2 %

\*\* tp = 380 μs, duty cycle < 2 %

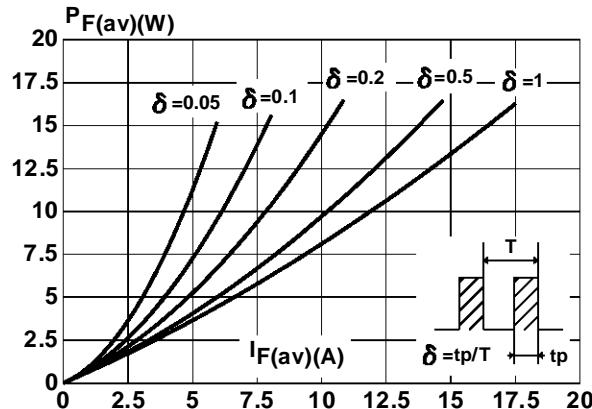
To evaluate the conduction losses use the following equation :

$$P = 0.65 \times I_{F(AV)} + 0.016 \times I_{F}^2(RMS)$$

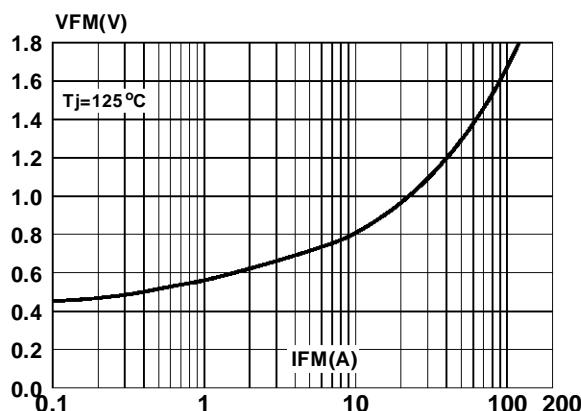
### RECOVERY CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
trr	T <sub>j</sub> = 25°C	I <sub>F</sub> = 0.5A	I <sub>rr</sub> = 0.25A		25	ns
		I <sub>F</sub> = 1A	dI <sub>F</sub> /dt = -50A/μs		40	
tfr	T <sub>j</sub> = 25°C	I <sub>F</sub> = 1A	tr = 10 ns		15	ns
V <sub>FP</sub>	T <sub>j</sub> = 25°C	I <sub>F</sub> = 1A	tr = 10 ns		2	V

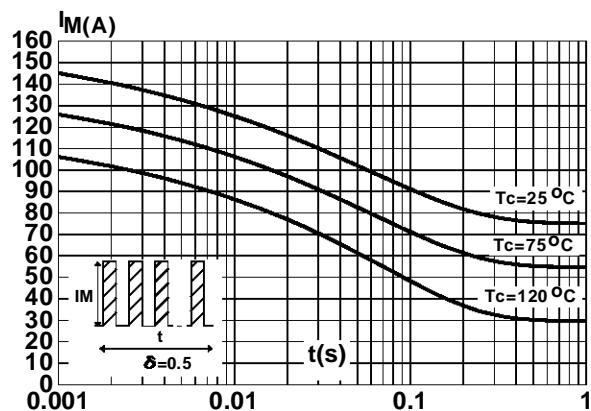
**Fig.1 :** Average forward power dissipation versus average forward current.



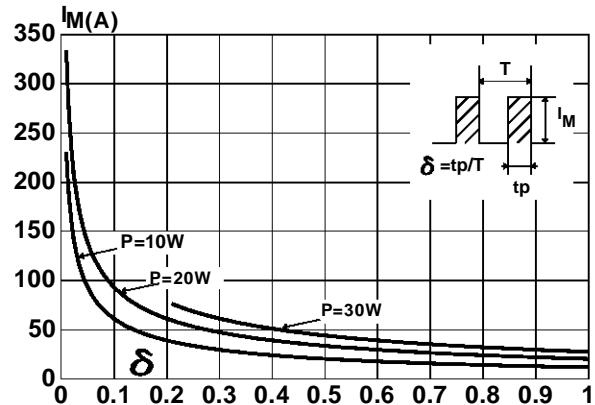
**Fig.3 :** Forward voltage drop versus forward current (maximum values).



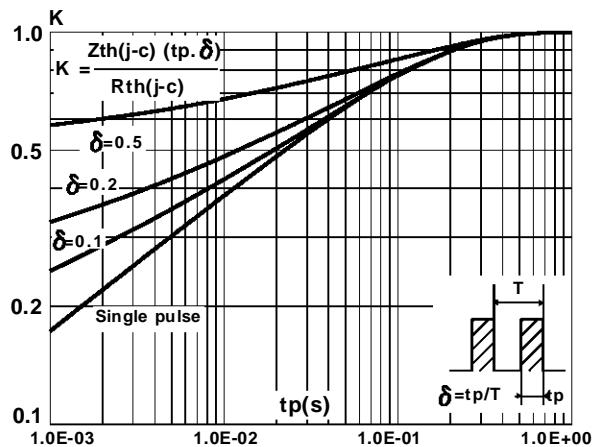
**Fig.5 :** Non repetitive surge peak forward current versus overload duration.  
(SOT93, TO247)



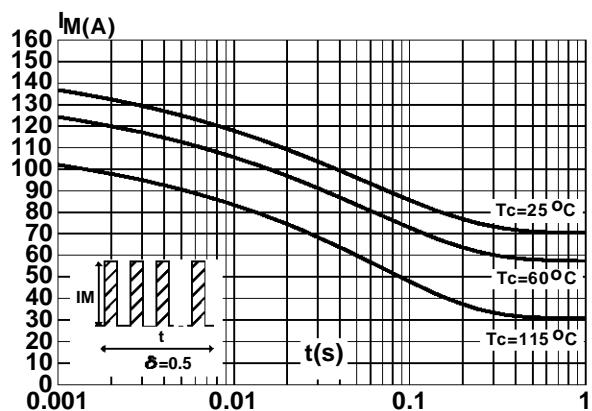
**Fig.2 :** Peak current versus form factor.



**Fig.4 :** Relative variation of thermal impedance junction to case versus pulse duration.

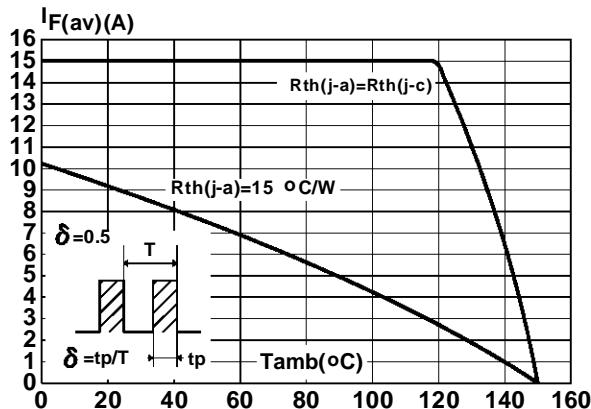


**Fig.6 :** Non repetitive surge peak forward current versus overload duration.  
(TOP3I)

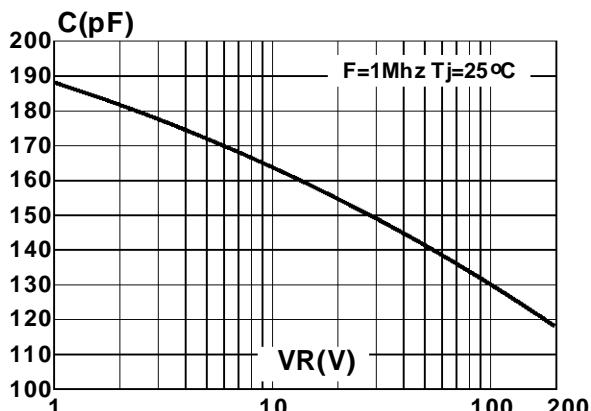


## BYW99P/PI/W

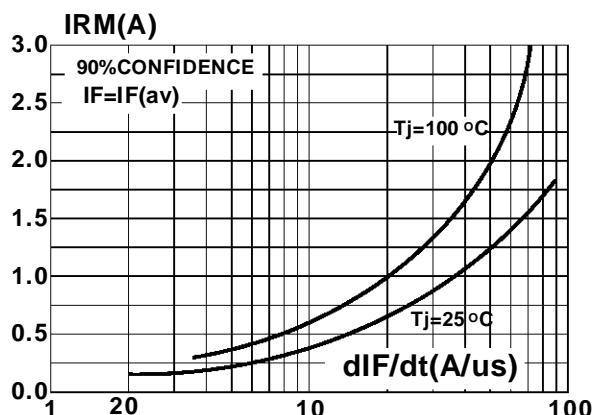
**Fig.7** : Average current versus ambient temperature.  
(duty cycle : 0.5) (SOT93, TO247)



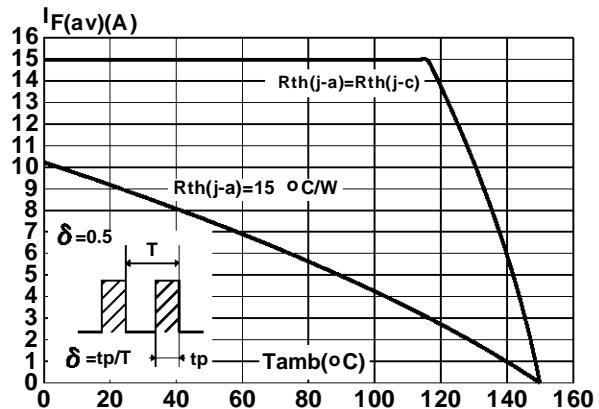
**Fig.9** : Junction capacitance versus reverse voltage applied (Typical values).



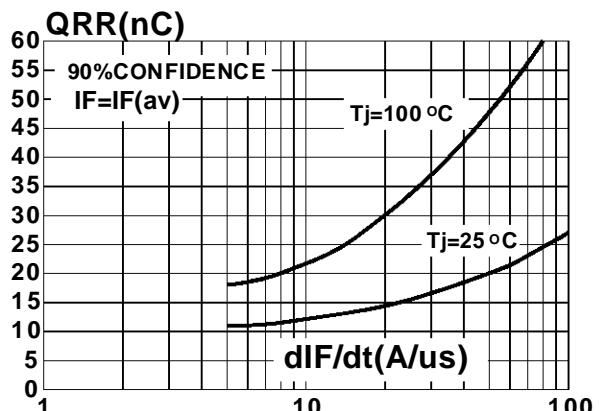
**Fig.11** : Peak reverse current versus  $dI_F/dt$ .



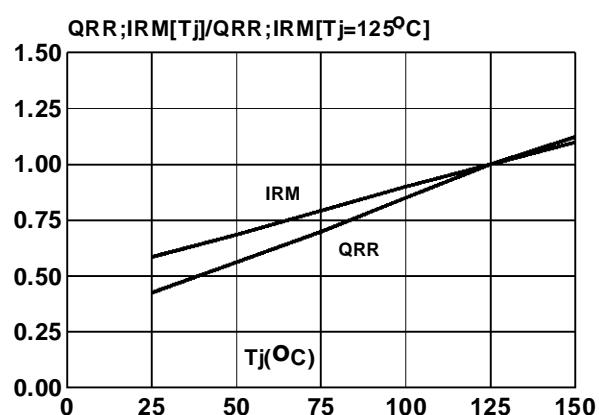
**Fig.8** : Average current versus ambient temperature.  
(duty cycle : 0.5) (TOP3I)



**Fig.10** : Recovery charges versus  $dI_F/dt$ .

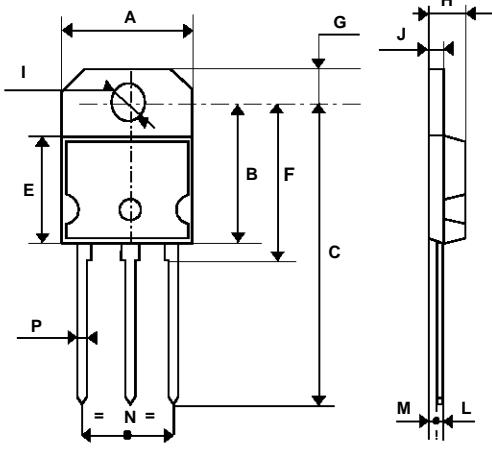


**Fig.12** : Dynamic parameters versus junction temperature.



## PACKAGE MECHANICAL DATA

SOT93



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	14.7	15.2	0.578	0.596
B		16.2		0.637
C	31 typ		1.220 typ	
D	18 typ		0.708 typ	
E		12.2		0.480
G	3.95	4.15	0.155	0.163
H	4.7	4.9	0.185	0.193
I	4	4.1	0.157	0.161
J	1.9	2.1	0.062	0.075
L	0.5	0.78	0.019	0.030
M	2.5 typ		0.098 typ	
N	10.8	11.1	0.425	0.437
P	1.1	1.3	0.043	0.051

Cooling method : C

Marking : Type number

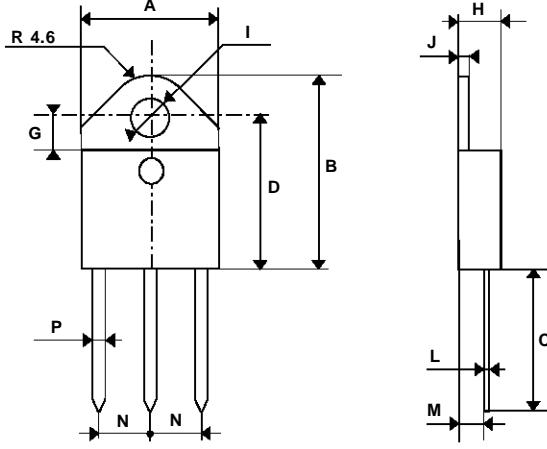
Weight : 5.3 g

Recommended torque value : 0.8m.N

Maximum torque value : 1.0m.N

## PACKAGE MECHANICAL DATA

TOP3I (isolated)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	15.10	15.50	0.594	0.611
B	20.70	21.10	0.814	0.831
C	14.30	15.60	0.561	0.615
D	16.10	16.50	0.632	0.650
G	3.40	-	0.133	-
H	4.40	4.60	0.173	0.182
I	4.08	4.17	0.161	0.164
J	1.45	1.55	0.057	0.062
L	0.50	0.70	0.019	0.028
M	2.70	2.90	0.106	0.115
N	5.40	5.65	0.212	0.223
P	1.20	1.40	0.047	0.056

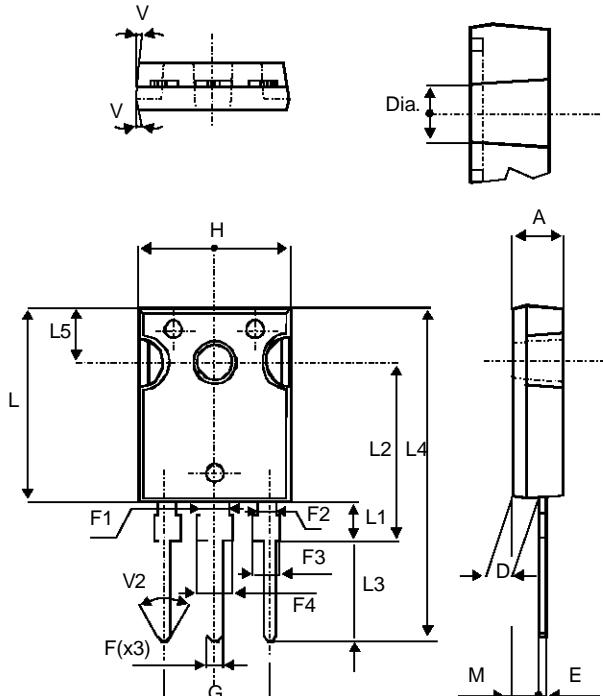
Cooling method : C

Marking : Type number

Weight : 4.7 g

Recommended torque value : 0.8m.N

Maximum torque value : 1.0m.N

**BYW99P/PI/W****PACKAGE MECHANICAL DATA**  
TO247


REF.	DIMENSIONS					
	Millimeters			Inches		
Typ.	Min.	Max.	Typ.	Min.	Max.	
A		4.70	5.30		0.190	0.210
D		2.20	2.60		0.0866	0.102
E		0.40	0.80		0.015	0.031
F		1.00	1.40		0.039	0.055
F1	3.00			0.118		
F2	2.00			0.078		
F3		2.00	2.40		0.078	0.094
F4		3.00	3.40		0.118	0.133
G	10.90			0.429		
H		15.30	15.90		0.602	0.625
L		19.70	20.30		0.775	0.799
L1	3.70	4.30		0.145	0.169	
L2	18.50			0.728		
L3	10.50			0.413		
L4	34.60			1.362		
L5	5.50			0.216		
M		2.00	3.00		0.078	0.118
V	5°			5°		
V2	60°			60°		
Dia.		3.55	3.65		0.139	0.143

Cooling method : C

Marking : Type number

Weight : 4.4 g

Recommended torque value : 0.8m.N

Maximum torque value : 1.0m.N

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